

DNP FID1
DNP FID2
DNP FID3

PCB Number: TIDA-00535
PCB Rev: E1

PCB LOGO
Texas Instruments
PCB LOGO
Pb-Free Symbol
PCB LOGO
FCC disclaimer

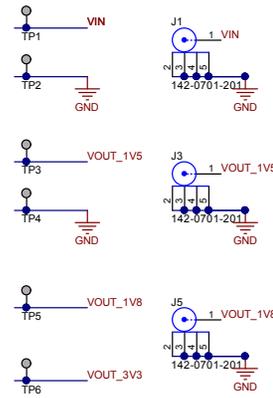
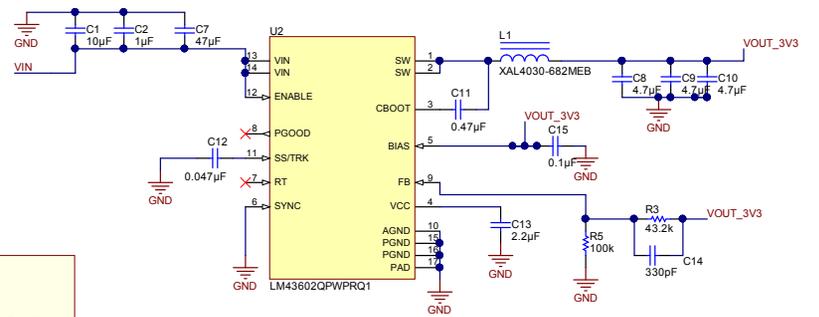
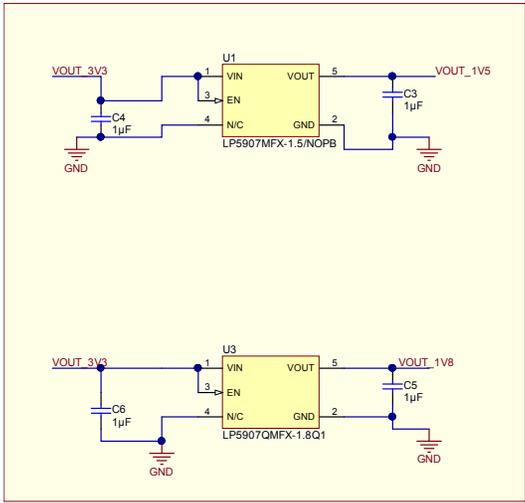
Label Table	
Variant	Label Text
001	

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 7/21/2015
TID #: 00535	Project Title: TIDA-00535	
Number: TIDA-00535 Rev: E1	Sheet Title:	
SW Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA-00535_Sheet1_SchDoc	Size: B
Engineer: Antony Carvajales	Contact: http://www.ti.com/support	http://www.ti.com

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